

Peter Borgesen

List of Publications by Year in descending order

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32
papers

873
citations

471509

17
h-index

677142

22
g-index

32
all docs

32
docs citations

32
times ranked

380
citing authors

#	ARTICLE	IF	CITATIONS
1	Recrystallization and Precipitate Coarsening in Pb-Free Solder Joints During Thermomechanical Fatigue. Journal of Electronic Materials, 2012, 41, 241-252.	2.2	99
2	On the root cause of Kirkendall voiding in Cu ₃ Sn. Journal of Materials Research, 2011, 26, 455-466.	2.6	91
3	Pb-Free Solder: New Materials Considerations for Microelectronics Processing. MRS Bulletin, 2007, 32, 360-365.	3.5	49
4	Assessment of Solder Joint Fatigue Life Under Realistic Service Conditions. Journal of Electronic Materials, 2014, 43, 4472-4484.	2.2	41
5	Effects of Strain Rate and Amplitude Variations on Solder Joint Fatigue Life in Isothermal Cycling. Journal of Electronic Packaging, Transactions of the ASME, 2016, 138, .	1.8	41
6	Assessing the risk of “Kirkendall voiding” in Cu ₃ Sn. Microelectronics Reliability, 2011, 51, 837-846.	1.7	39
7	A Mechanistic Thermal Fatigue Model for SnAgCu Solder Joints. Journal of Electronic Materials, 2018, 47, 2526-2544.	2.2	38
8	Toward a Better Understanding of the Effect of Cu Electroplating Process Parameters on Cu ₃ Sn Voiding. Journal of Electronic Materials, 2012, 41, 302-312.	2.2	36
9	Improving Copper Electrodeposition in the Microelectronics Industry. IEEE Transactions on Components and Packaging Technologies, 2010, 33, 127-137.	1.3	34
10	Multiscale modeling of thermoelectric generators for the optimized conversion performance. International Journal of Heat and Mass Transfer, 2013, 62, 435-444.	4.8	34
11	Correlation Between Solder Joint Fatigue Life and Accumulated Work in Isothermal Cycling. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2015, 5, 1292-1299.	2.5	34
12	Damage Evolution in Lead Free Solder Joints in Isothermal Fatigue. Journal of Electronic Packaging, Transactions of the ASME, 2015, 137, .	1.8	30
13	Effect of Cycling Amplitude Variations on SnAgCu Solder Joint Fatigue Life. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2018, 8, 1896-1904.	2.5	30
14	Sporadic Degradation in Board Level Drop Reliability - Those Aren't All Kirkendall Voids!. , 2007, , .		27
15	Recrystallization and $\{m Ag\}_3\{m Sn\}$ Particle Redistribution During Thermomechanical Treatment of Bulk Sn-3Ag-Cu Solder Alloys. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2013, 3, 1868-1875.	2.5	25
16	Accelerating the effects of aging on the reliability of lead free solder joints in a quantitative fashion. , 2009, , .		24
17	Statistical Variations of Solder Joint Fatigue Life Under Realistic Service Conditions. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2015, 5, 1284-1291.	2.5	24
18	Acceleration of the growth of Cu ₃ Sn voids in solder joints. Microelectronics Reliability, 2012, 52, 1121-1127.	1.7	22

#	ARTICLE	IF	CITATIONS
19	Assessment of PCB pad cratering resistance by joint level testing. , 2008, , .		20
20	Reliability and failure mechanism of solder joints in thermal cycling tests. , 2013, , .		20
21	On the nature of pad cratering. , 2009, , .		18
22	On the Assessment of the Life of SnAgCu Solder Joints in Cycling With Varying Amplitudes. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2013, 3, 430-440.	2.5	17
23	Effects of latent damage of recrystallization on lead free solder joints. Microelectronics Reliability, 2014, 54, 447-456.	1.7	16
24	Multiscale modeling of Thermoelectric Generators for conversion performance enhancement. International Journal of Heat and Mass Transfer, 2015, 81, 639-645.	4.8	15
25	Effects of Amplitude Variations on Deformation and Damage Evolution in SnAgCu Solder in Isothermal Cycling. Journal of Electronic Materials, 2018, 47, 2752-2760.	2.2	14
26	Controlling Cu electroplating to prevent sporadic voiding in CuIn3Sn. , 2009, , .		10
27	Effects of microstructure evolution on damage accumulation in lead-free solder joints. , 2010, , .		9
28	Effects of Solder Paste Volume and Reflow Profiles on the Thermal Cycling Performance of Mixed SnAgCu/SnPb Solder Joints. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2011, 1, 1205-1213.	2.5	6
29	Effect of microstructure evolution on Pb-free solder joint reliability in thermomechanical fatigue. , 2012, , .		5
30	Fatigue Testing of Copper Nanoparticle-Based Joints and Bonds. Journal of Electronic Packaging, Transactions of the ASME, 2022, 144, .	1.8	3
31	A multiscale modeling of Thermoelectric Generators for conversion efficiency optimization. , 2012, , .		2
32	Early transient creep of single crystal SnAgCu solder joints. Journal of Materials Science: Materials in Electronics, 0, , .	2.2	0